



SamHop Microelectronics Corp.

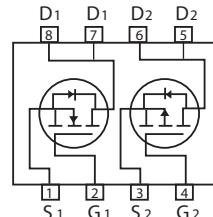
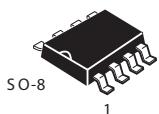
SDM8401

August , 2002

Dual Enhancement Mode Field Effect Transistor (N and P Channel)

PRODUCT SUMMARY (N-Channel)		
V _{DSS}	I _D	R _{D(S)ON} (m Ω) TYP
30V	6A	18.5 @ V _{GS} = 10V
		25 @ V _{GS} = 4.5V

PRODUCT SUMMARY (P-Channel)		
V _{DSS}	I _D	R _{D(S)ON} (m Ω) TYP
-30V	-4.5A	38.5 @ V _{GS} = -10V
		57.5 @ V _{GS} = -4.5V

ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Gate-Source Voltage	V _{GS}	±20	±20	V
Drain Current-Continuous ^a @ T _J =125°C -Pulsed ^b	I _D	±6.0	±4.5	A
	I _{DM}	±18.0	±15	A
Drain-Source Diode Forward Current ^a	I _S	1.7	-1.7	A
Maximum Power Dissipation ^a	P _D	2.0		W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150		°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R _{θJA}	62.5	°C/W
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N-Channel ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250µA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V		1		µA
Gate-Body Leakage	I _{GSS}	V _{GS} = ±16V, V _{DS} = 0V			±100	nA
ON CHARACTERISTICS ^b						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250µA	1	1.5	3	V
Drain-Source On-State Resistance	R _{DSON}	V _{GS} = 10V, I _D = 9A		18.5	21	m ohm
		V _{GS} = 4.5V, I _D = 7A		25	32	m ohm
On-State Drain Current	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	40			A
Forward Transconductance	g _F	V _{DS} = 10V, I _D = 20A		16		S
DYNAMIC CHARACTERISTICS ^c						
Input Capacitance	C _{ISS}	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz		950		pF
Output Capacitance	C _{OSS}			420		pF
Reverse Transfer Capacitance	C _{RSS}			110		pF
SWITCHING CHARACTERISTICS ^c						
Turn-On Delay Time	t _{D(ON)}	V _{DD} = 15V, I _D = 1A, V _{GS} = 10V, R _{GEN} = 6		7		ns
Rise Time	t _r			30		ns
Turn-Off Delay Time	t _{D(OFF)}			14		ns
Fall Time	t _f			54		ns
Total Gate Charge	Q _g	V _{DS} = 15V, I _D = 9A, V _{GS} = 10V		25.2	35	nC
		V _{DS} = 15V, I _D = 9A, V _{GS} = 4.5V		12.1	14.6	nC
Gate-Source Charge	Q _{gs}	V _{DS} = 15V, I _D = 9A, V _{GS} = 10V		5.12		nC
Gate-Drain Charge	Q _{gd}			4.8		nC

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P-Channel ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$		-1		μA
Gate-Body Leakage	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$		± 100		nA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1	-1.5	-3	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-4.5\text{A}$		38.5	53	m ohm
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-3.6\text{A}$		57.5	95	m ohm
On-State Drain Current	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}}=-5\text{V}, V_{\text{GS}}=-10\text{V}$	-20			A
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.5\text{A}$	5	10		S
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C_{ISS}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$		860		pF
Output Capacitance	C_{OSS}			457		pF
Reverse Transfer Capacitance	C_{RSS}			140		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	$t_{\text{D}(\text{ON})}$	$V_{\text{D}}=-15\text{V},$ $R_{\text{L}}=15$ $I_{\text{D}}=-1\text{A},$ $V_{\text{GEN}}=-10\text{V},$ $R_{\text{GEN}}=6$		9	20	ns
Rise Time	t_{r}			10	40	ns
Turn-Off Delay Time	$t_{\text{D}(\text{OFF})}$			37	90	ns
Fall Time	t_{f}			23	110	ns
Total Gate Charge	Q_{g}	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.9\text{A}, V_{\text{GS}}=-10\text{V}$		15	20	nC
		$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.9\text{A}, V_{\text{GS}}=-4.5\text{V}$		8	10	nC
Gate-Source Charge	Q_{gs}	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.9\text{A},$ $V_{\text{GS}}=-10\text{V}$		3		nC
Gate-Drain Charge	Q_{gd}			4		nC

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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS ^b						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0\text{V}, I_S = 1.7\text{A}$	N-Ch		0.77	1.2
		$V_{GS} = 0\text{V}, I_S = -1.7\text{A}$	P-Ch		-0.80	-1.2

Notes

a. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$.

b. Pulse Test Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

c. Guaranteed by design, not subject to production testing.

N-Channel

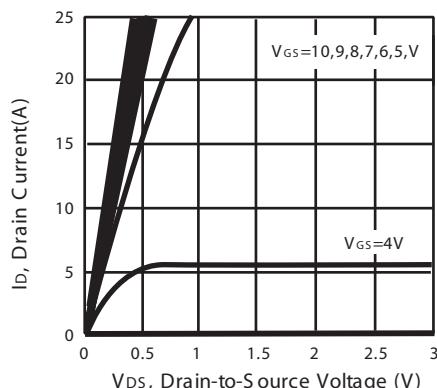


Figure 1. Output Characteristics

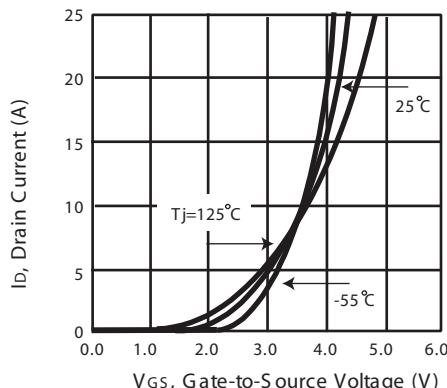


Figure 2. Transfer Characteristics

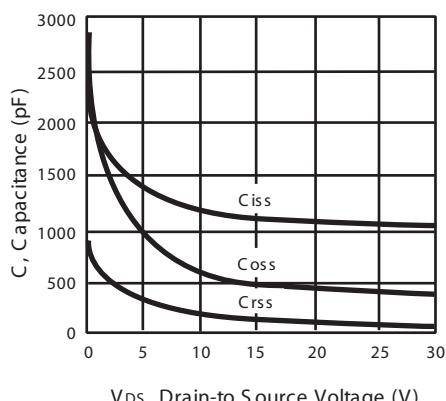


Figure 3. Capacitance

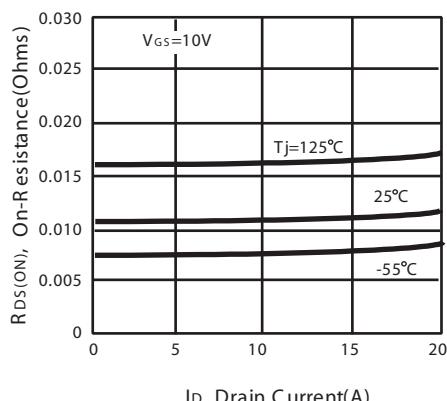


Figure 4. On-Resistance Variation with Drain Current and Temperature

N-Channel

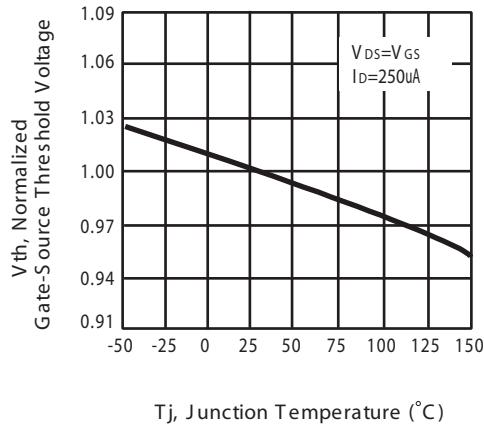


Figure 5. Gate Threshold Variation with Temperature

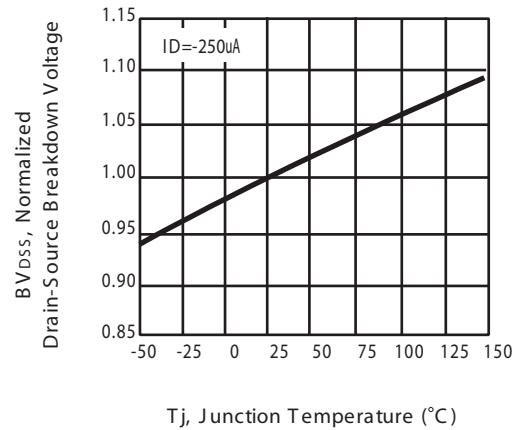
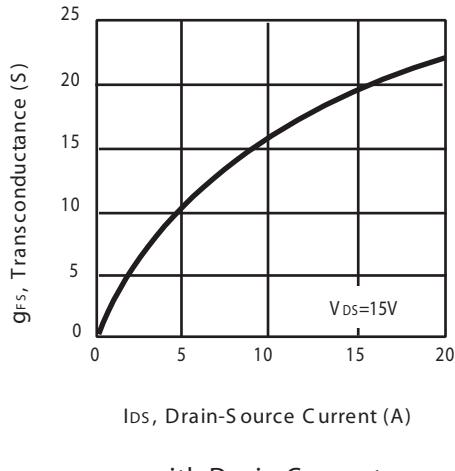


Figure 6. Breakdown Voltage Variation with Temperature



IDS, Drain-Source Current (A)

with Drain Current

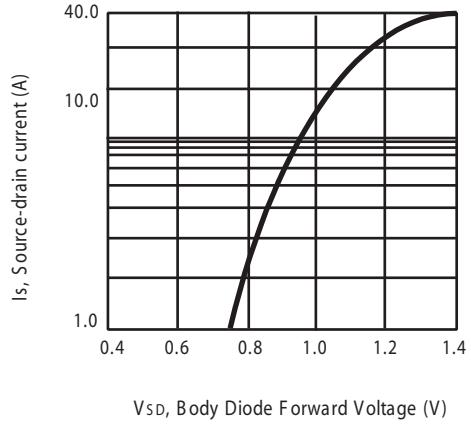


Figure 8. Body Diode Forward Voltage Variation with Source Current

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P-Channel

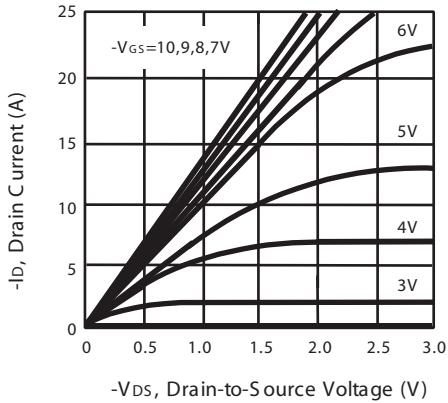


Figure 1. Output Characteristics

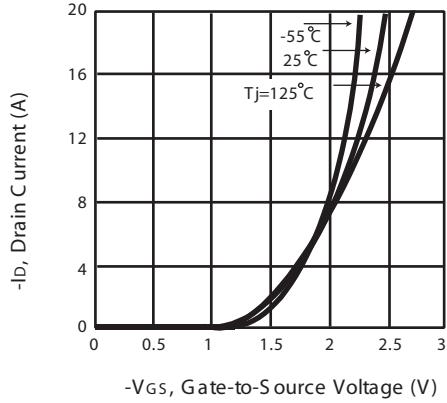


Figure 2. Transfer Characteristics

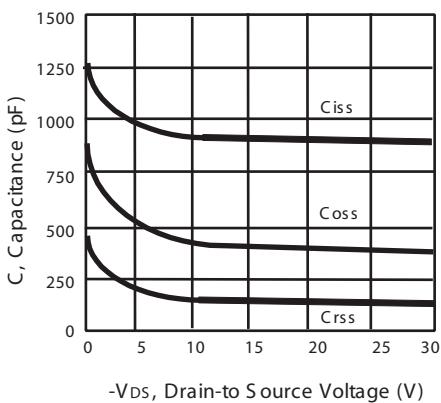


Figure 3. Capacitance

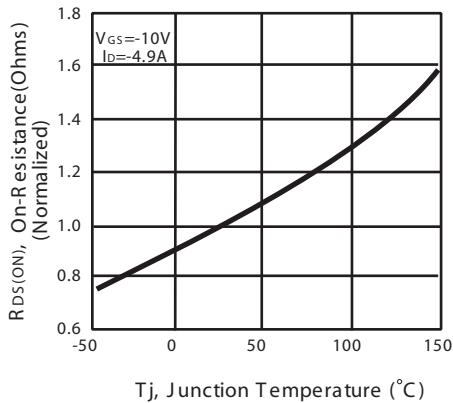


Figure 4. On-Resistance Variation with Temperature

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P-Channel

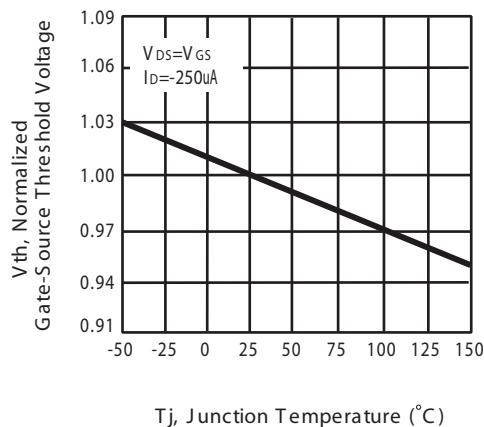


Figure 5. Gate Threshold Variation with Temperature

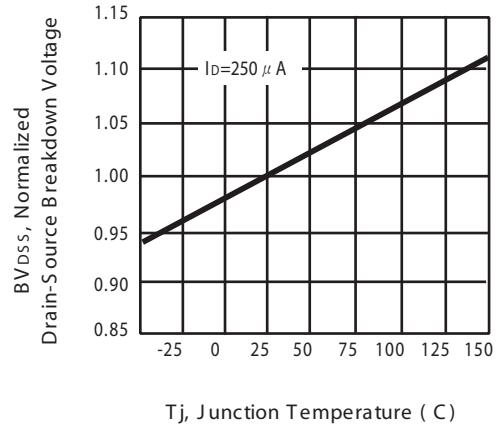


Figure 6. Breakdown Voltage Variation with Temperature

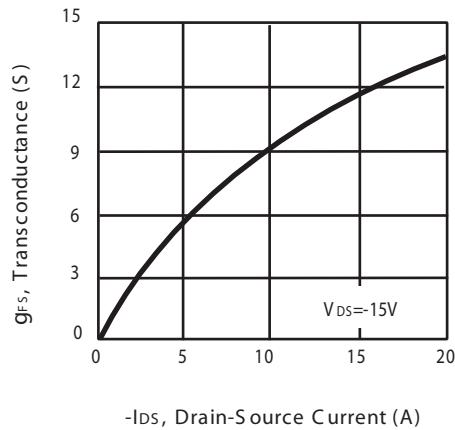


Figure 7. Transconductance Variation with Drain Current

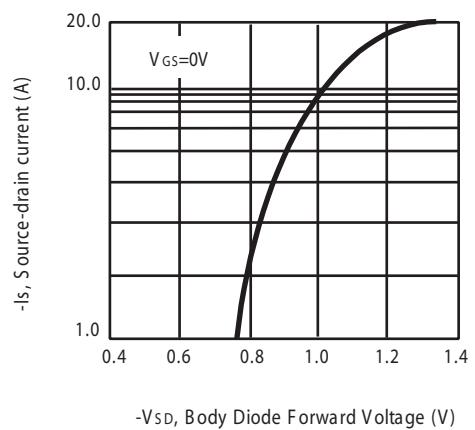
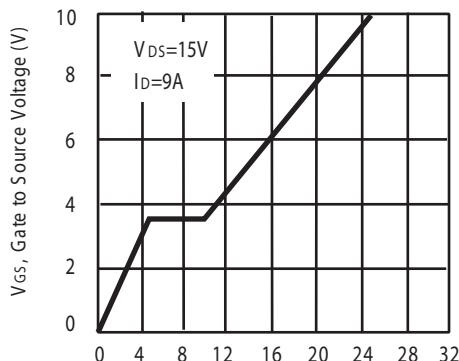


Figure 8. Body Diode Forward Voltage Variation with Source Current

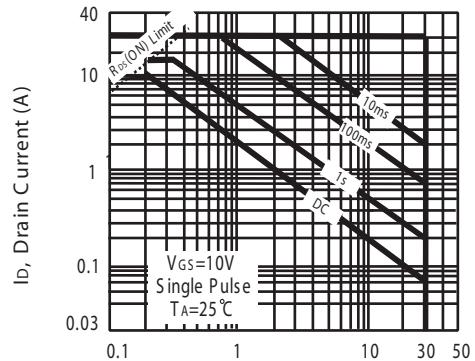
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N-Channel



Q_g , Total Gate Charge (nC)

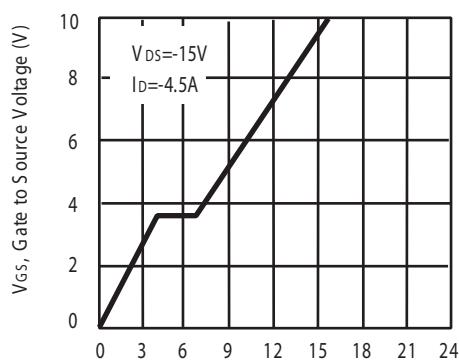
Figure 9. Gate Charge



V_{DS} , Drain-Source Voltage (V)

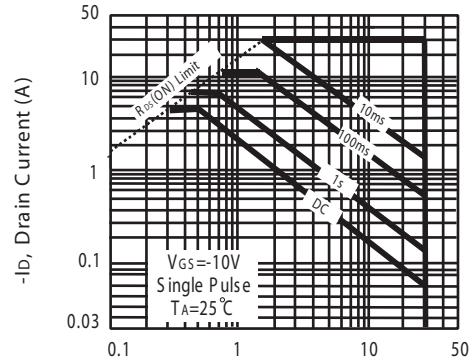
Figure 10. Maximum Safe Operating Area

P-Channel



Q_g , Total Gate Charge (nC)

Figure 9. Gate Charge



$-V_{DS}$, Body Diode Forward Voltage (V)

Figure 10. Maximum Safe Operating Area

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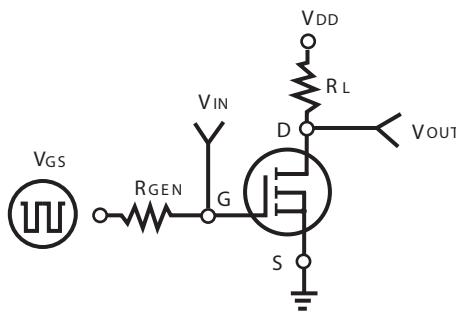


Figure 11. Switching Test Circuit

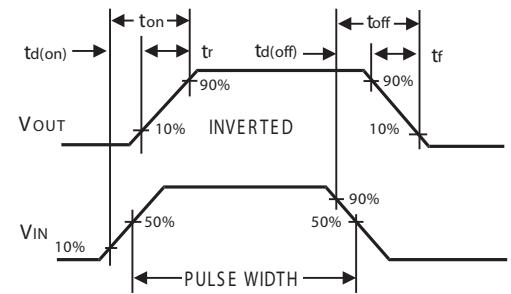


Figure 12. Switching Waveforms

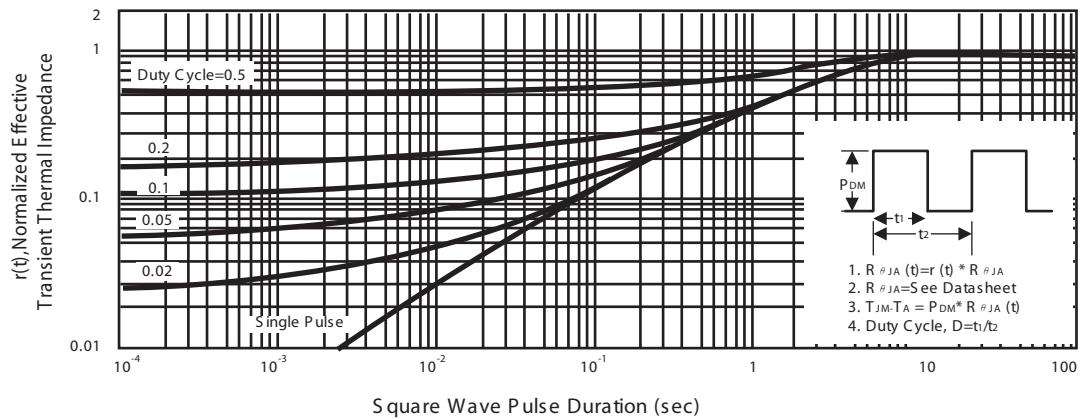


Figure 13. Normalized Thermal Transient Impedance Curve